

REMARKS/ARGUMENTS

Claims 16, 18, 27, 28, 30, 36, 37, 40, 45, 47, 49, 50, and 52 are amended (not for reasons relating to patentability), and claims 54 and 55 are new. Claims 16-18, 20-28, 30, 36-45, 47, and 49-55 are now pending. (Claims 1-15, 19, 29, 31-35, 46, and 48 are now or were previously canceled.) Applicants respectfully request reconsideration of the application.

Initially, Applicants thank the Examiner for the courtesy extended to Applicants' representatives at an in-person interview on April 24, 2008.

Claims 16-30 and 36-53 are rejected under 35 U.S.C. 112, first paragraph, as allegedly not complying with the written description requirement. In addition, the drawings were objected to as allegedly not showing every claimed feature. Applicants respectfully traverse these rejections and objections.

At least Figure 2A provides non-limiting examples of the shielding plane recited in the pending claims. Coupling pads 32 and 34 in Figure 2A are non-limiting examples of conduct structures for contactlessly receiving signals. Moreover, the specification states that power plane 70 and ground plane 72 can "also shield DUT 18 from electrical interference." (Specification paragraph [039], lines 7-8.) The specification also states that DUT 18 can be a semiconductor die that is unsingulated from—and thus a part of—a wafer. (Specification paragraph [035], line 5-6.) DUT 18 in Figure 2A thus illustrates a non-limiting example of a portion of a wafer, and power plane 70 or ground plane 72 illustrates a non-limiting example of a shielding plane. Figure 2A thus fully supports and illustrates the shielding plane on a wafer recited in the claims.

Moreover, Figure 2A in combination with Figure also support and illustrate a shielding plane on a wafer. The specification states that "wafer 124 may include shielding as generally described above with respect to Figures 2A and 2B." (Specification paragraph [059], last line.) As discussed above, the specification also states that power plane 70 and ground plane 72 can "shield DUT 18 from electrical interference." (Specification paragraph [039], lines 7-8.) Thus, the non-limiting, exemplary wafer 124 illustrated in Figure 7 can include the power plane 70 and/or ground plane 72 of Figure 2A, which can be shielding planes. The combination of Figures 7 and 2A thus also fully support and illustrate the shielding plane and wafer recited in the claims.

For at least the foregoing reasons, the specification fully supports and the drawings sufficiently illustrate a shielding plane on a wafer as claimed. Applicants therefore request

withdrawal of both the rejection under 35 USC 112, first paragraph and the objection to the drawings.

In view of the foregoing, Applicants submit that all objections and rejections are overcome and all of the pending claims are allowable and the application is in condition for allowance. If the Examiner believes that a discussion with Applicants' attorney would be helpful, the Examiner is invited to contact the undersigned or Ken Burraston (801) 426-2100.

Respectfully submitted,

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